

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT6787027

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MATHIAS WENDT	10/16/2019
ANDREAS WEIMAR	11/27/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	OSRAM OPTO SEMICONDUCTORS GMBH
<b>Street Address:</b>	LEIBNIZSTR. 4
<b>City:</b>	REGENSBURG
<b>State/Country:</b>	GERMANY
<b>Postal Code:</b>	93055
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17361435
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(215)656-3301
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	215-656-3381
<b>Email:</b>	pto.phil@us.dlapiper.com
<b>Correspondent Name:</b>	IP GROUP OF DLA PIPER LLP (US)
<b>Address Line 1:</b>	ONE LIBERTY PLACE
<b>Address Line 2:</b>	1650 MARKET ST, SUITE 5000
<b>Address Line 4:</b>	PHILADELPHIA, PENNSYLVANIA 19103
<b>ATTORNEY DOCKET NUMBER:</b>	EHF-19-1455DIV/369254-695
<b>NAME OF SUBMITTER:</b>	LESLIE J. HOOD
<b>SIGNATURE:</b>	/LJH/
<b>DATE SIGNED:</b>	06/29/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 4</b>	
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source=CombinedDeclarationAndAssignment#page3.tif	



**EHF-19-1455**

**2016P02791WOUS / P2017,0521 US N (JSK/MRB)**

**COMBINED DECLARATION/ASSIGNMENT**

WHEREAS, we

Mathias Wendt of Hausen, Germany  
Andreas Weimar of Regensburg, Germany

(hereinafter referred to as "the undersigned"), have made an invention entitled METHOD OF FASTENING A SEMICONDUCTOR CHIP ON A LEAD FRAME, AND ELECTRONIC COMPONENT, identified in International Application No. PCT/EP2018/059928 and US Application No. 16/604,252,

the above-identified application was made or authorized to be made by the persons executing this Declaration;

we believe that we are the original joint inventors of a claimed invention in the application;

we hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, OSRAM Opto Semiconductors GmbH, with offices at Leibnizstr. 4, 93055 Regensburg, Germany (hereinafter referred to as "assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

EAST\169399499.1

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the dates set forth below.

October 16, 2019  
Date

\_\_\_\_\_  
Date

Mathias Wendt  
Mathias Wendt

\_\_\_\_\_  
Andreas Weimar

EHF-19-1455  
2016P02791WOUS / P2017,0521 US N (JSK/MRB)

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EASTV169399499.1

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EXECUTED on the dates set forth below.

\_\_\_\_\_  
Date

27th november 2019

Date

\_\_\_\_\_  
Mathias Wendt

*Andreas Weimar*

Andreas Weimar